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CLAIMS 1-12 ARE CANCELED.

13. A circuit board manufacturing method comprising the steps of:

forming a through hole on an insulator layer and then filling said through hole with a conductive paste;

dispersing and forming a protective agent in mottle-like on an adhesion surface of a conductor foil which

provides a wiring layer, and dispersing and forming each dimension of adhesion surface regions where said protective agent does not exist in a state that the plurality of said conductive powder constituting said conductive paste is set to be capable of abutting on the said wiring layer;

sticking said conductor foil to said insulator layer; and

electrically and physically joining said conductor foil and said conductive paste by abutting the plurality of said conductive powders and said conductor foil each other by means of heating and pressurizing for said insulator layer.

14. The circuit board manufacturing method according to Claim 13, wherein said protective agent is stored and placed into a minute recess in said adhesion surface by abutting a adhesive surface of said conductor foil on a protective agent containing liquid, while a storage amount of said protective agent for said minute recess is controlled by adjusting an abutting time of said protective agent containing liquid, thereby setting each dimension of the adhesion surface regions where said protective agent does not exist.

15. The circuit board manufacturing method according to Claim 13, wherein said protective agent is stored and placed into the minute recess in the adhesion surface by abutting the adhesion of said conductor foil on the protective agent containing liquid, while the storage amount of said protective agent for said minute recess is adjusted by adjusting a protective agent containing amount of said protective agent containing liquid, thereby setting each dimension of the adhesion surface regions where said protective agent does not exist.

16. The circuit board manufacturing method according to Claim 13, wherein a layer containing said protective agent is formed on the adhesion surface of said conductor foil, and then the protective agent layer is polished to such an extent that a top portion of a minute protrusion on said adhesion surface may be exposed, while a exposed amount of said top portion is adjusted at a time of polishing, thereby setting each dimension of the adhesion surface regions where said protective agent does not exist.